



TUF0060 是一种具有导热能力的底部填充胶，可以极大地提高芯片的散热效率，增强芯片与 PCB 板之间的粘接力，提升芯片的长期使用可靠性。

TUF0060 is an adhesive with exceptional thermal conductivity specifically designed for underfill applications in chip packaging. It significantly enhances the chip's heat dissipation efficiency. Additionally, it strengthens the bond between the chip and the PCB, bolstering the long-term reliability of the chip.

Features 特性

- Thermal Conductivity 导热
- Low Viscosity 低粘度
- Low Density 低密度
- High Reliability 高可靠性

Applications 产品应用

- Consumer Electronics 消费电子
- Communication equipment 通讯设备
- Power supply controller 电源控制系统
- Smart Wearable Product 智能穿戴产品

Operating Requirements 操作要求

- Warm up to room temperature before use 使用前回温到室温
- Any moisture should be immediately wiped off 任何水分应立即擦除
- Cannot be repeatedly frozen 不能反复冷冻

Property 特性	Typical Value 典型值	Unit 单位	Test Method 测试方法
Composition 主要成分	Epoxy Filled with Silica 氧化硅粉体填充环氧树脂		—
Color 颜色	Off White 米白色	—	Visual 目视
Thermal Conductivity 导热系数	0.6	W/m·K	ASTM D5470
Viscosity 粘度	5000	mPa·s	CP51, 25°C Speed 20 rpm
Density 密度	1.85	g/cm ³	ASTM D792
Cure Schedule 固化条件	3min@150°C	—	—
Tg 玻璃化转变温度	110	°C	TMA
CTE 热膨胀系数	50 & 140	ppm/°C	TMA
Storage Modulus 储能模量	5.0	GPa	DMA
Die Shear Strength 粘接强度	10	Kg	3*3mm ² Si on FR4
Pot Life 使用期	3	day	25°C
Shelf Life 保存期	6	month	-20°C
RoHS Compliance 合规性	YES	—	—

All technical information stated in this technical data have been confirmed that all the technical parameters are reliable after harsh testing and evaluation of the products. Before you use our products, please carefully evaluate and decide whether the product meets your requirement and you need to take all the risks and responsibilities to use.

此技术资料里所有陈述的技术信息，全部是基于本公司对自身产品在经过严格的测试评估后，证明各项技术参数指标是值得信赖的前提下编写的。在您使用我们公司产品之前，请充分评估该产品是否符合您的使用需求，您需要承担使用的全部风险和责任。